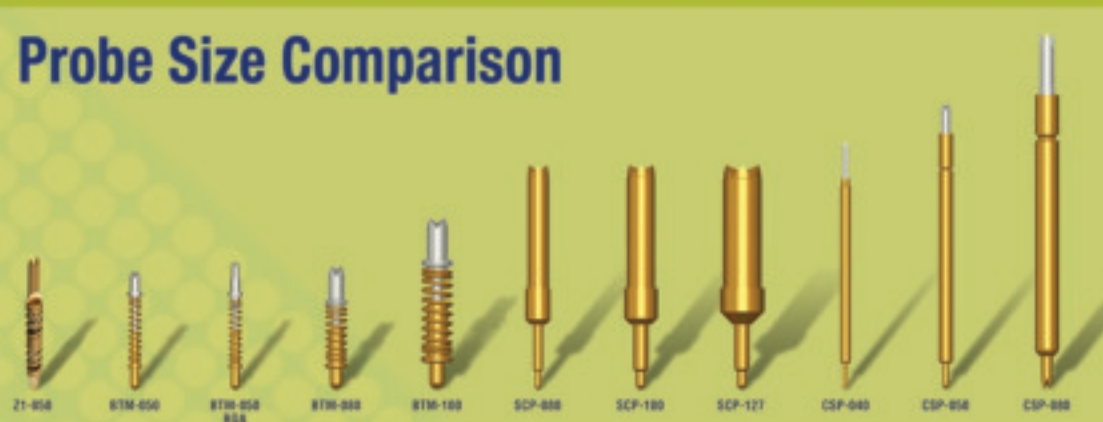




Technical Specifications Semiconductor Test Pin Product Portfolio

		Pitch	OAL	Test Height	Maximum Total Travel*	Spring Force	Mech Life**	Avg. DC Resistance***	Current	Inductance	Bandwidth	Operating Temperature	
INTERFACE	FINAL TEST (Hi-Perf)	Bantam	0.5mm	2.86mm	2.49mm	.37mm	31g	1,000k	<50mΩ	1.5A	0.95nH	12.9GHz	-55°C to 155°C
			0.8mm	3.00mm	2.62mm	.38mm	28g	1,000k	<50mΩ	2.0A	0.77nH	15.7GHz	-55°C to 155°C
			1.0mm	4.17mm	3.45mm	.72mm	39g	1,000k	<50mΩ	3.5A	1.30nH	9.7GHz	-55°C to 155°C
	FINAL TEST (Std-Perf)	Z1	0.4mm	3.17mm	2.66mm	.51mm	34g	1,000k	<50mΩ	3.0A	TBD	TBD	-55°C to 155°C
			0.5mm	3.35mm	2.79mm	.56mm	34g	1,000k	<50mΩ	3.0A	1.01nH	27.6GHz	-55°C to 155°C
			0.8mm	3.35mm	2.66mm	.69mm	34g	1,000k	<50mΩ	TBD	TBD	TBD	-55°C to 155°C
		Z2	0.4mm	3.17mm	2.66mm	.51mm	34g	1,000k	<100mΩ	2.5A	TBD	TBD	-55°C to 155°C
			0.5mm	3.35mm	2.79mm	.56mm	34g	1,000k	<100mΩ	2.5A	1.01nH	8.1GHz	-55°C to 155°C
			0.8mm	3.35mm	2.66mm	.69mm	34g	1,000k	<100mΩ	TBD	TBD	TBD	-55°C to 155°C
	CSP	0.4mm	6.02mm	5.51mm	.51mm	24.1g	500k	<100mΩ	2.0A	1.71nH	6.8GHz	-55°C to 105°C	
		0.5mm	5.94 - 6.96mm	5.44 - 6.45mm	.50mm	19.8 - 28.4g	500k	<100mΩ	2.0A	1.50 - 1.76nH	6.8 - 8.1GHz	-55°C to 155°C	
		0.8mm	6.15 - 8.69mm	5.38 - 7.92mm	.77mm	31.2g	500k	<100mΩ	3.0A	1.23 - 1.81nH	5.3 - 9.2GHz	-55°C to 155°C	
1.0/1.27mm		8.89mm	8.00mm	.89mm	59.7g	500k	<100mΩ	5.0A	3.10nH	3.8GHz	-55°C to 155°C		
BURN-IN	SCP	0.8mm	5.84mm	5.08mm	.76mm	34g	1,000k	<50mΩ	5.0A	1.27nH	6.0GHz	-55°C to 155°C	
		1.0mm	5.84mm	5.08mm	.76mm	34g	1,000k	<50mΩ	7.0A	1.40nH	6.8GHz	-55°C to 155°C	
		1.27mm	5.84mm	5.08mm	.76mm	34g	1,000k	<50mΩ	9.0A	1.40nH	7.6GHz	-55°C to 155°C	
Z8	0.4mm	3.17mm	2.66mm	.51mm	34g	20k	100mΩ	3.0A	TBD	4.5GHz	-55°C to 155°C		
	0.5mm	3.35mm	2.79mm	.56mm	34g	20k	100mΩ	3.0A	1.01nH	4.5GHz	-55°C to 155°C		
	0.8mm	3.35mm	2.66mm	.69mm	34g	20k	100mΩ	TBD	TBD	4.5GHz	-55°C to 155°C		

Probe Size Comparison



Specifications are subject to change without notification and are for reference only.

*Includes both DUT and board side travel

**Life specifications are based on lab results but are dependent on cleaning frequency and the specific customer application including DUT materials, handler kit, maintenance, etc.

***Contact resistance will increase over time due to solder build-up and wear

